

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chin-Sheng Yang	09/07/2010
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12888393
CORRESPONDENCE DATA	
Fax Number: (703)997-4517 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 3027291562 Email: Patent.admin.uspto.cr@naipo.com Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506 Address Line 4: Merrifield, VIRGINIA 22116	
ATTORNEY DOCKET NUMBER:	NAUP1013USA4
NAME OF SUBMITTER:	HSIANG HUANG
Total Attachments: 2 source=945814#page1.tif source=945814#page2.tif	

CH \$40.00 12888393

501299146

PATENT
REEL: 025031 FRAME: 0669

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Chin-Sheng Yang Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.
Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"SEMICONDUCTOR ASSEMBLY"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this SEP 07 2010 (Date of signing). (请登明人務必簽署上列日期。)

(Type name of inventor)

Chin-Sheng Yang

Signature of INVENTOR

Chin-sheng Yang

PATENT

RECORDED: 09/22/2010

REEL: 025031 FRAME: 0671